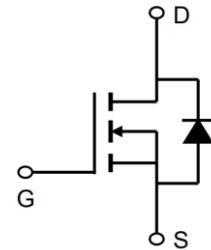


100V N-Channel Enhancement Mode MOSFET

Description

The AP1N10I uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



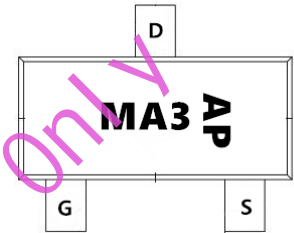
General Features

$V_{DS} = 100V$ $I_D = 1.5A$

$R_{DS(ON)} < 500m\Omega$ @ $V_{GS} = 10V$

Application

- Atomizer
- Load switch
- Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP1N10I	SOT23L	MA3-AP	3000

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	1.5	A
$I_D @ T_A = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	1.2	A
I_{DM}	Pulsed Drain Current ²	6	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ³	1.2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	104	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	75	$^\circ C/W$



100V N-Channel Enhancement Mode MOSFET**Electrical Characteristics (T_J=25°C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100			V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V			1	μA
IGSS1	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
IGSS2		V _{GS} =±10V, V _{DS} =0V			±50	nA
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.2	1.8	2.5	V
RDS(ON)	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =1.5A		430	500	mΩ
RDS(ON)		V _{GS} =4.5V, I _D =1A		460	550	
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1MHZ		232		pF
C _{oss}	Output Capacitance			23		pF
C _{rss}	Reverse Transfer Capacitance			24		pF
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =50V, I _D =2A		6.47		nC
Q _{gs}	Gate-Source Charge			1.27		nC
Q _{gd}	Gate-Drain Charge			1.29		nC
Q _{rr}	Reverse Recovery Charge	I _F =2A, di/dt=100A/us		18.1		nC
t _{rr}	Reverse Recovery Time			36.9		ns
tD(on)	Turn-on Delay Time	V _{GS} =10V, V _{DS} =50V, I _D =1.3A R _{GEN} =1Ω		4.6		ns
t _r	Turn-on Rise Time			18		ns
tD(off)	Turn-off Delay Time			16		ns
t _f	Turn-off fall Time			27.4		ns
V _{SD}	Diode Forward Voltage	I _S =1.5A, V _{GS} =0V			1.2	V

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

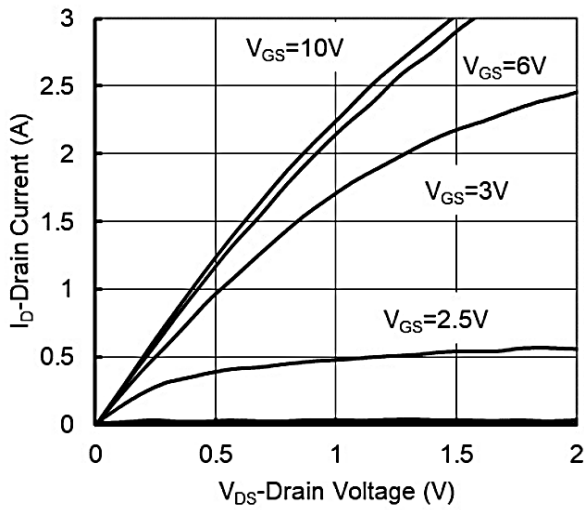


Figure1. Output Characteristics

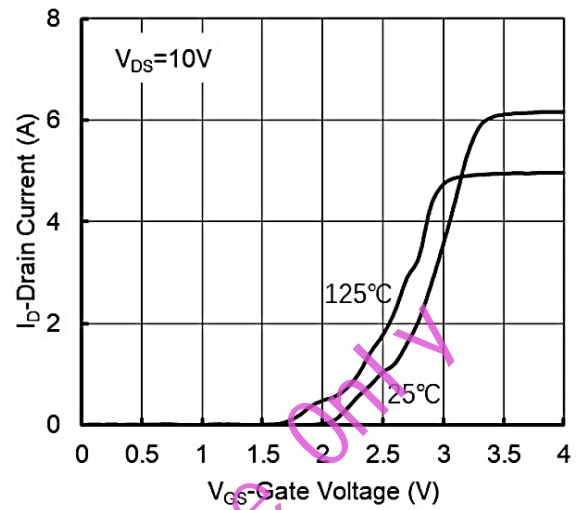


Figure2. Transfer Characteristics

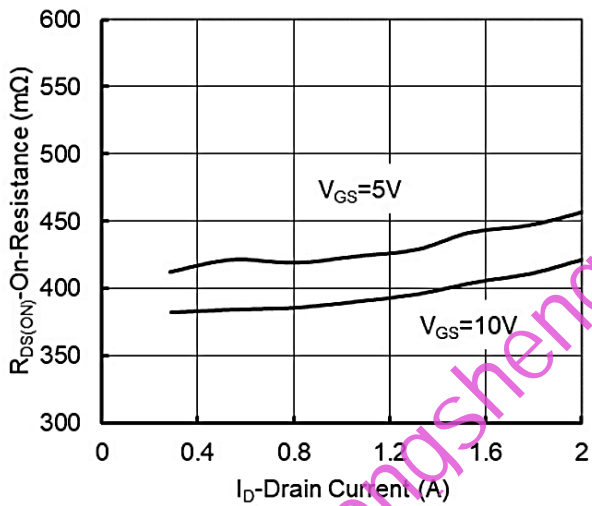


Figure 3: On-Resistance vs. Drain Current

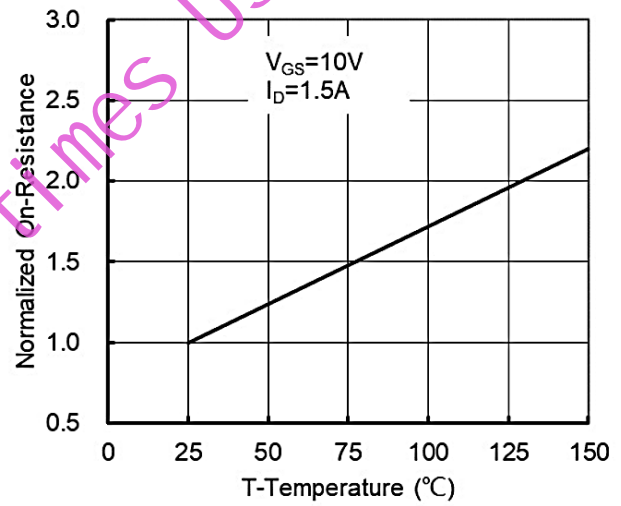


Figure 4: On-Resistance vs. Junction Temperature

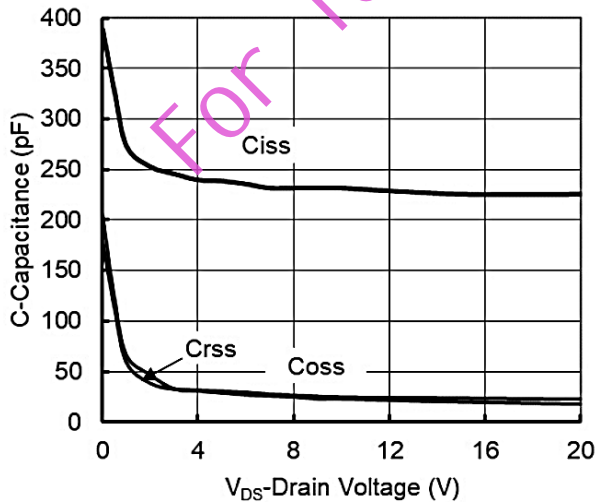


Figure5. Capacitance Characteristics

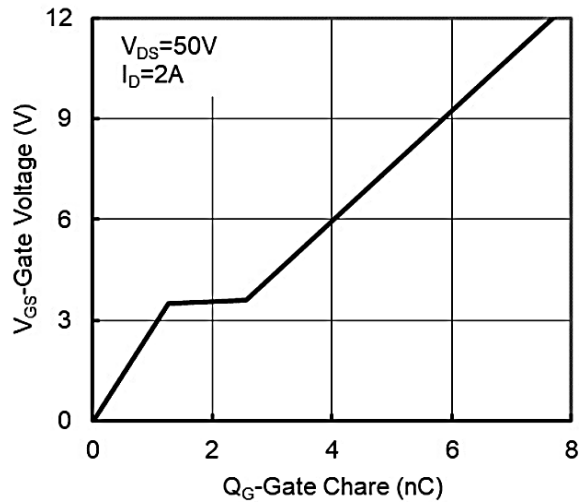


Figure6. Gate Charge

100V N-Channel Enhancement Mode MOSFET

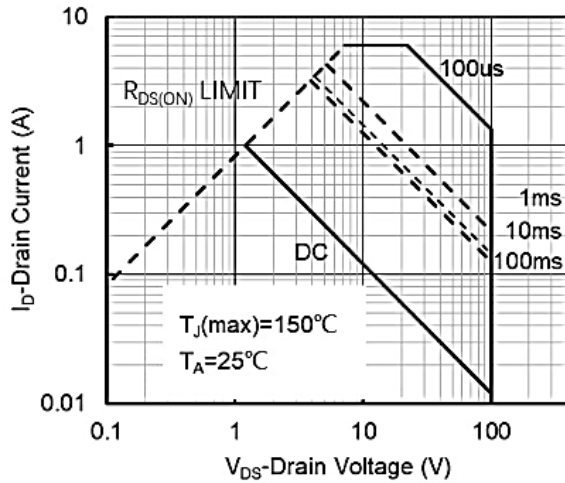


Figure 7. Safe Operation Area

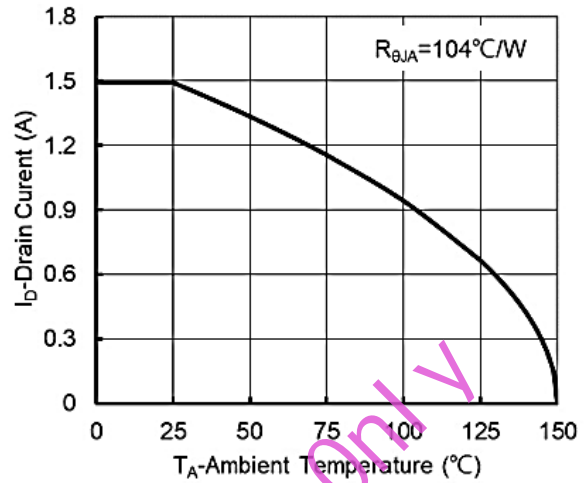


Figure 8. Maximum Continuous Drain Current vs Ambient Temperature

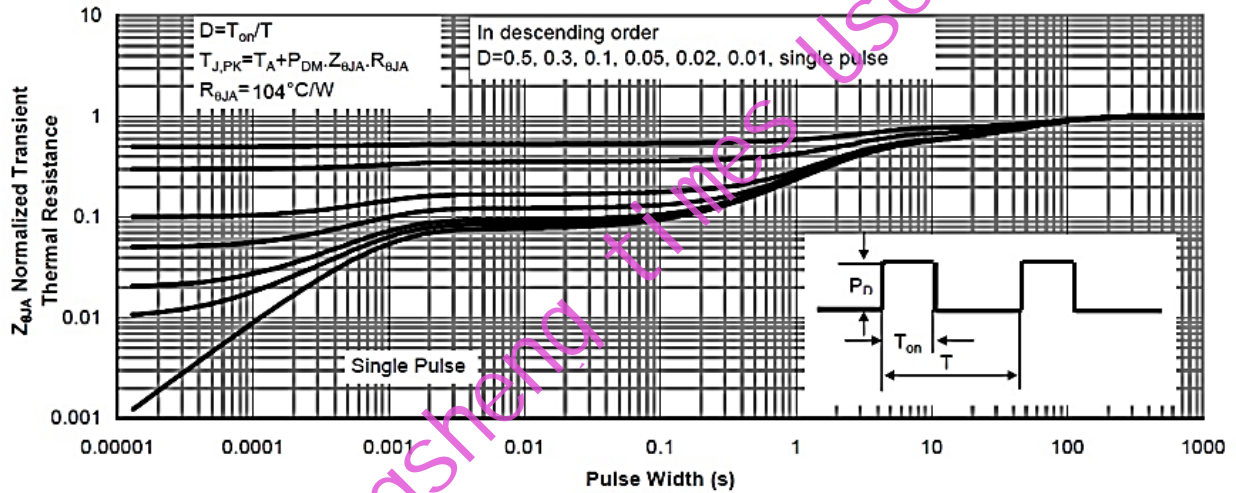
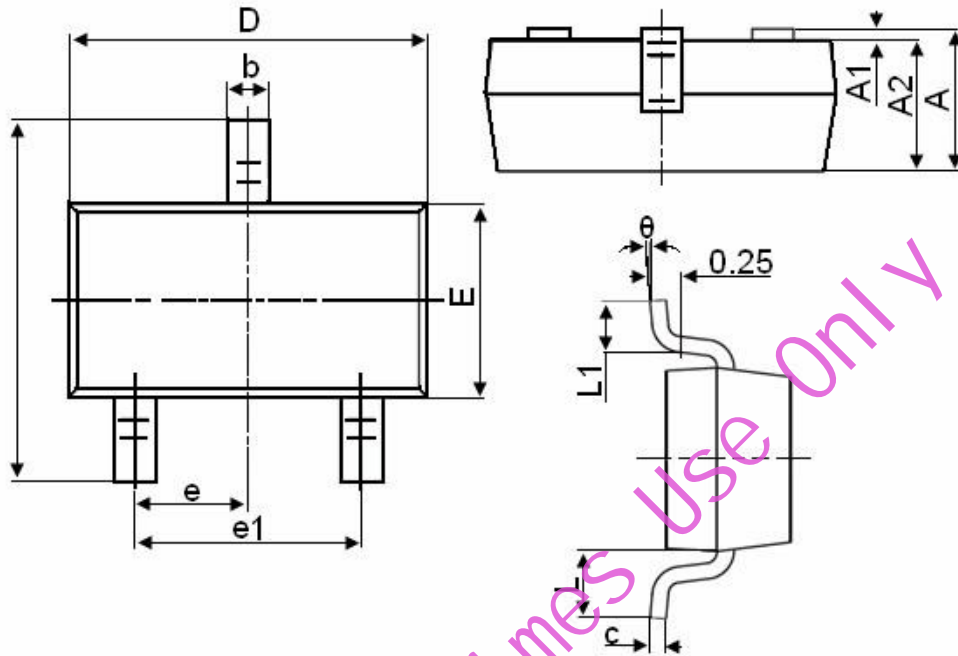


Figure 9. Normalized Maximum Transient Thermal Impedance

Package Mechanical Data-SOT23-XC-Single



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
theta	0°	8°

100V N-Channel Enhancement Mode MOSFET**Attention**

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AP1N10I

100V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2020/5/1	Initial release

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